

UM10521

TEA1721 isolated universal mains flyback converter demo board

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User manual

Document information

| Info | Content |
|-----------------|--|
| Keywords | TEA1721AT, isolated, universal mains, AC/DC conversion, flyback converter, Switched Mode Power Supply (SMPS) |
| Abstract | This user manual describes the application of the TEA1721ADB1061 demo board. The demo board is designed as an isolated 12 V, and 3.3 V AC/DC SMPS for supplying up to 5 W into a load. |



Revision history

| Rev | Date | Description |
|-----|----------|-------------|
| v.1 | 20120308 | first issue |

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1. Introduction

WARNING

Lethal voltage and fire ignition hazard



The non-insulated high voltages that are present when operating this product, constitute a risk of electric shock, personal injury, death and/or ignition of fire.

This product is intended for evaluation purposes only. It shall be operated in a designated test area by personnel qualified according to local requirements and labor laws to work with non-insulated mains voltages and high-voltage circuits. This product shall never be operated unattended.

This user manual describes the application of the TEA1721ADB1061 demo board. The demo board is designed as an isolated 12 V and 3.3 V AC/DC SMPS for supplying up to 5 W to a load.

The switch-mode converter operates in flyback mode at a maximum frequency of around 51 kHz. Overcurrent and short-circuit protection are built in. The power consumption is between 10 mW and 20 mW under no-load conditions.

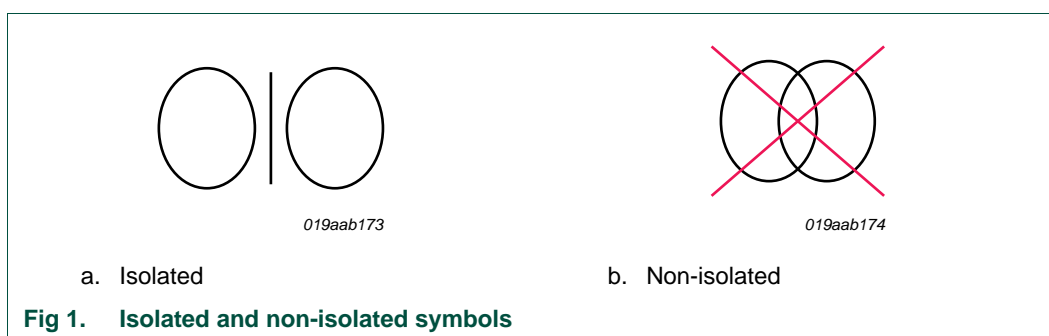
EMI filtering for compliance with EN55022 has been implemented in this circuit.

1.1 Features and benefits

- Compatible with Universal Mains
- Inrush current limitation
- EMI filtering to meet EMC requirements of EN55022

2. Safety Warning

The demo board is powered by AC mains voltage. Avoid touching the board when power is applied. An isolated housing is obligatory when used in uncontrolled, non-laboratory environments. Always provide galvanic isolation of the mains phase using a variable transformer. The following symbols identify isolated and non-isolated devices.



3. Specification

Table 1. Demo board specification

| Parameter | Value | Comment |
|--------------------------|--|--|
| AC line input voltage | 85 V (AC) to 265 V (AC) | universal mains; supplied to the J1.1 and J1.2 terminals |
| Output voltage | 12 V (DC) and 3.3 V (DC) | supplied from connectors: J2.1 = 0 V, GND J2.2 = 3.3 V J2.3 = 12 V |
| Maximum output current | 12 V = 400 mA 3.3 V = 400 mA | - - |
| Maximum output power | 5 W | - |
| Output voltage stability | ±5 % | strongly depends on the magnetic coupling of the secondary and auxiliary winding of transformer T1 |
| Efficiency | 79.3 % at 115 V (AC)/60 Hz 80 % at 230 V (AC)/50 Hz | - - |
| Operating temperature | -40 °C to 85 °C | - |
| EMC Compliance | EN55022 | - |
| Board dimensions | 41 mm × 51 mm × 25 mm | L × B × H |



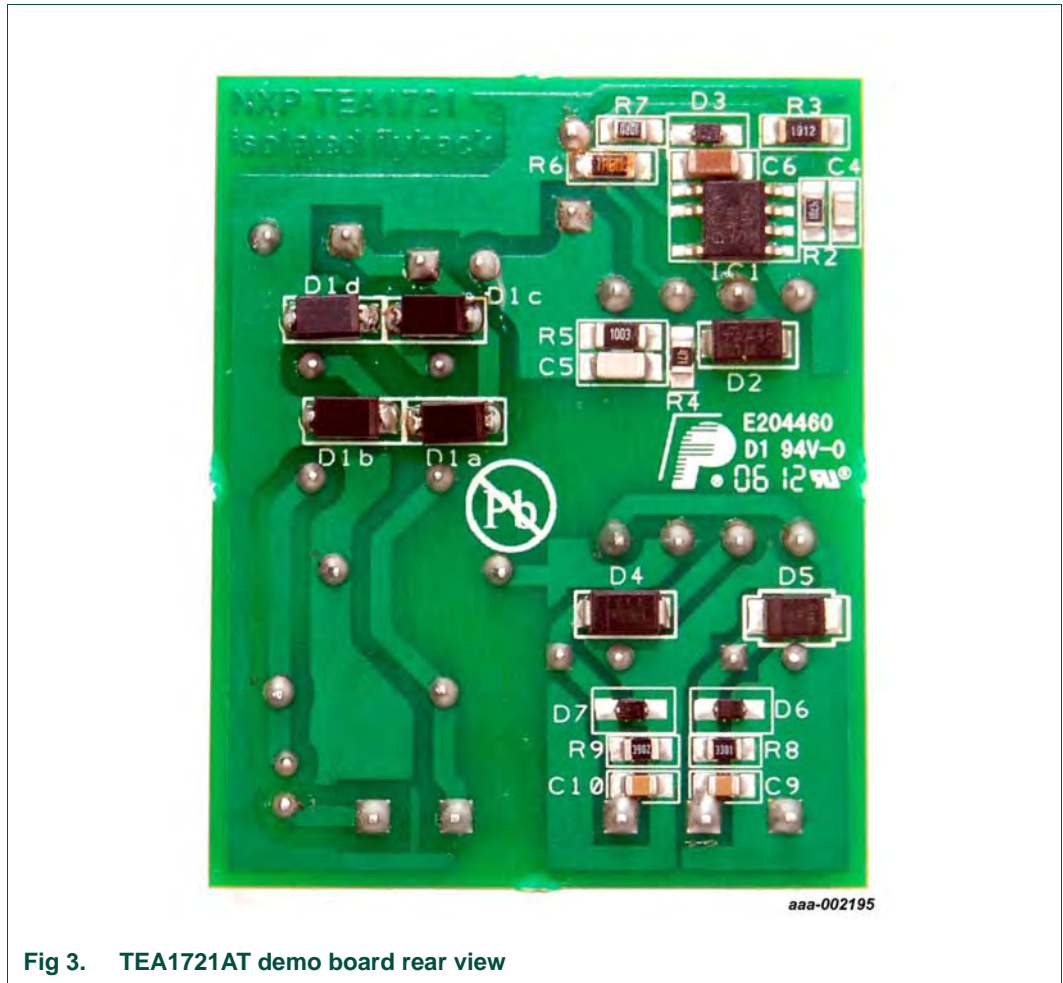


Fig 3. TEA1721AT demo board rear view

4. Demo board connections

The isolated universal mains flyback demo board has an input and an output terminal block.

The input terminal block (right on the picture) is connected to the mains voltage. Live and Neutral wires can be connected randomly to this terminal block.

The output terminal block (left on the picture) provides the 12 V and 3.3 V output voltages, both referenced to a common ground (GND).

Remark: Mount the board in a shielded or isolated box for demonstration purposes.

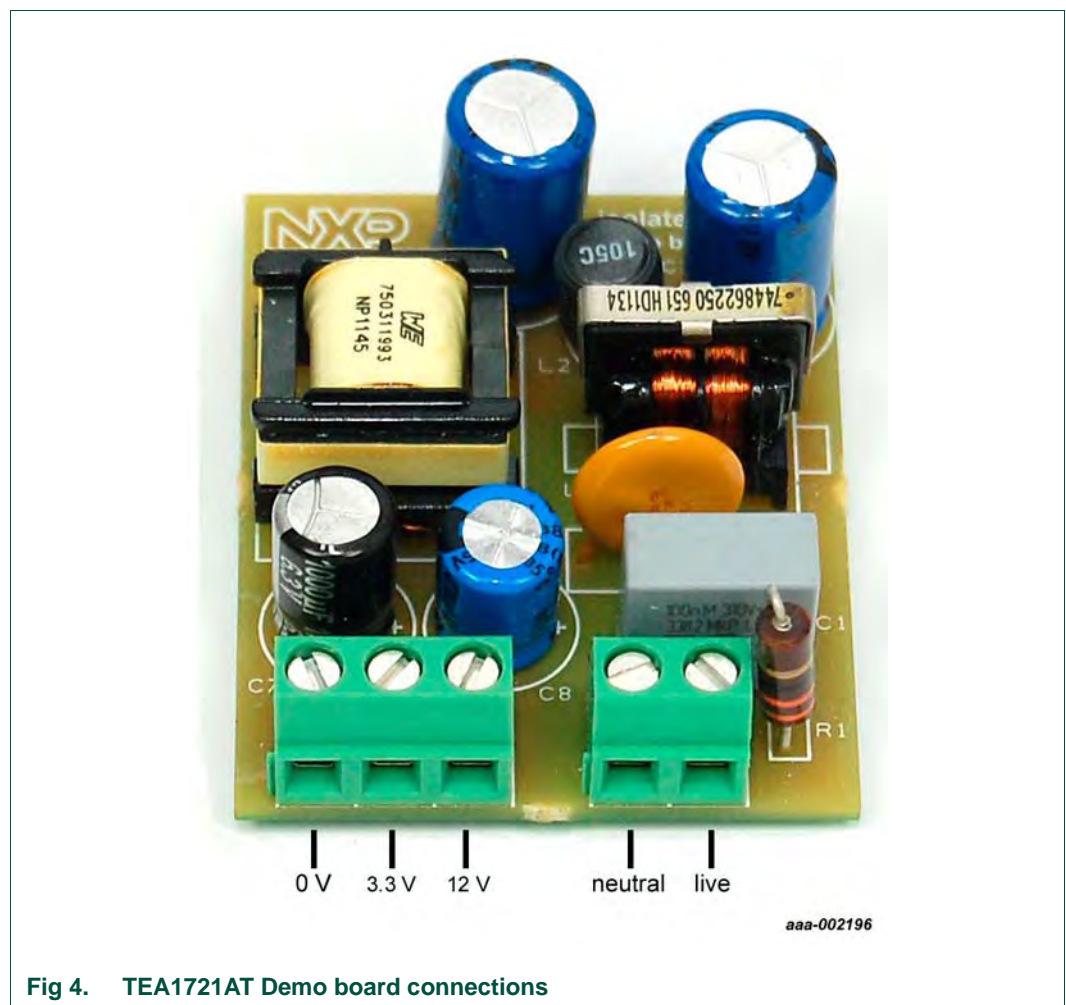


Fig 4. TEA1721AT Demo board connections

5. Demo board schematic

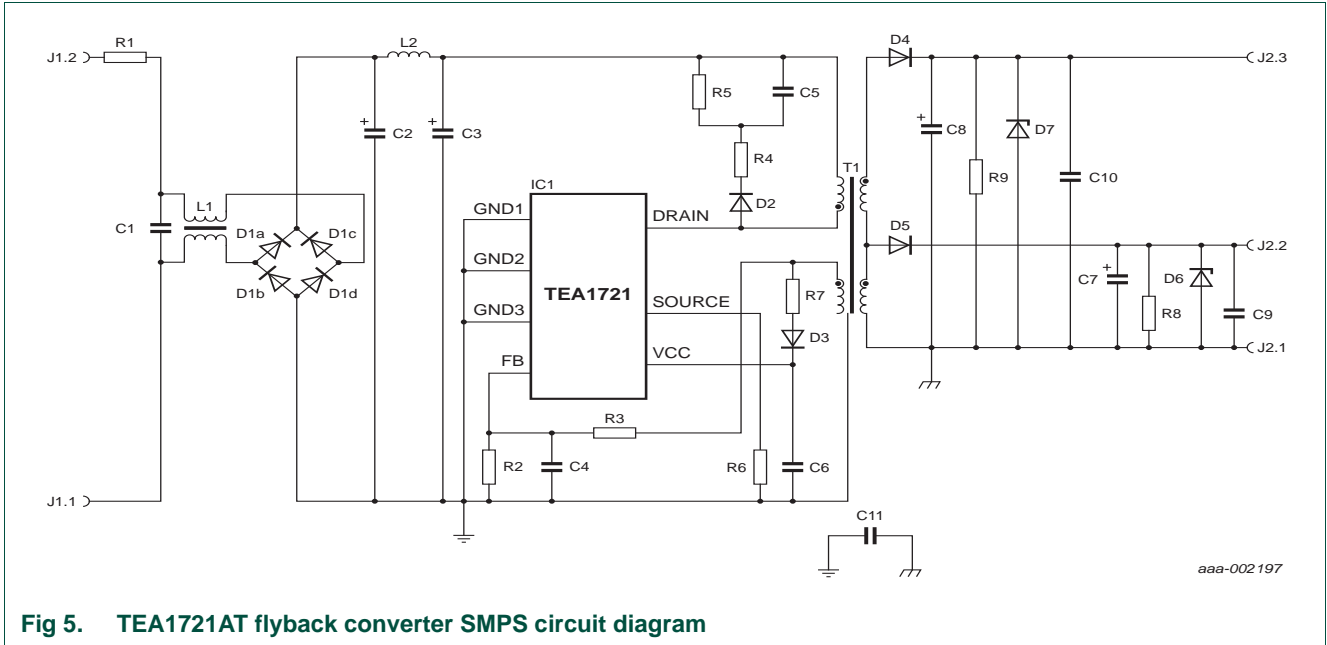


Fig 5. TEA1721AT flyback converter SMPS circuit diagram

6. PCB components

Table 2. Demo board components

| Reference | Description and value | Part number | Manufacturer |
|------------------|--|-------------|--------------------|
| C1 | 100 nF; 275 V (AC); 4E pitch | - | - |
| C2 | electrolytic capacitor; Ø10 mm maximum; 4.7 µF; 400 V; 2E pitch | - | - |
| C3 | electrolytic capacitor; Ø10 mm maximum; 4.7 µF; 400 V; 2E pitch | - | - |
| C4 | 10 pF; 25 V; 0805 | - | - |
| C5 | 220 pF; 500 V; 1206 | - | - |
| C6 | 2.2 µF; 50 V; 1206 | - | - |
| C7 | electrolytic capacitor; Ø10 mm maximum; 1 mF; 6.3 V; 1.5E pitch | - | - |
| C8 | electrolytic capacitor; Ø10 mm maximum; 470 µF; 16 V; 1.5E pitch | - | - |
| C9 | 100 nF; 25 V; 0805 | - | - |
| C10 | 100 nF; 25 V; 0805 | - | - |
| C11 | Y-capacitor; 2.2 nF; 1 kV; 4E pitch | - | - |
| D1a | S1M; SMA | - | Fairchild |
| D1b | S1M; SMA | - | Fairchild |
| D1c | S1M; SMA | - | Fairchild |
| D1d | S1M; SMA | - | Fairchild |
| D2 | S1M; SMA | - | Fairchild |
| D3 | BAS316; SOD323 | - | NXP Semiconductors |
| D4 | Schottky; 100 V; 1 A; 10MQ100NTRPBF; SMA | - | Vishay |
| D5 | PMEG4050EP; SOD128 | - | NXP Semiconductors |
| D6 | BZX384-C3V6; SOD323 | - | NXP Semiconductors |
| D7 | BZX384-B12; SOD323 | - | NXP Semiconductors |
| IC1 | TEA1721AT; SO7 | - | NXP Semiconductors |
| J1.1; J1.2 | 2-pole terminal block; 2E pitch | 1729128 | Phoenix |
| J2.1; J2.2; J2.3 | 3-pole terminal block; 2E pitch | 1729131 | Phoenix |
| L1 | 2 × 25 mH; 80 mA; 250 V (AC) | 744862250 | Würth Elektronik |
| L2 | 1 mH; 80 mA; 1.5E pitch | 22R105 | Murata |
| R1 | carbon resistor; mounted upright; 33 Ω; 1E pitch | - | - |
| R2 | 4.7 kΩ; 1 %; 0805 | - | - |
| R3 | 19.1 kΩ; 1 %; 1206 ^[2] | - | - |
| R4 | 470 Ω; 0805 | - | - |
| R5 | 100 kΩ; 0.5 W; 1206 | - | - |
| R6 | 1.8 Ω; 0.25 W; 1206 | - | - |
| R7 | 10 Ω; 0805 | - | - |

Table 2. Demo board components ...continued

| Reference | Description and value | Part number | Manufacturer |
|-----------|--|-------------|------------------|
| R8 | 3.3 k Ω ; 0805 | - | - |
| R9 | 39 k Ω ; 0805 | - | - |
| T1 | Custom-made transformer ^[1] | 750311993 | Würth Elektronik |

[1] Custom transformer: primary winding inductance 2.4 mH; turns ratio Primary: Secondary: Auxiliary = 6.5 : 1 : 1. The secondary winding must have a tap for the 3.3 V output voltage.

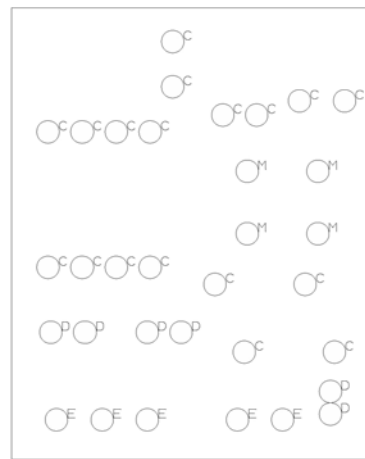
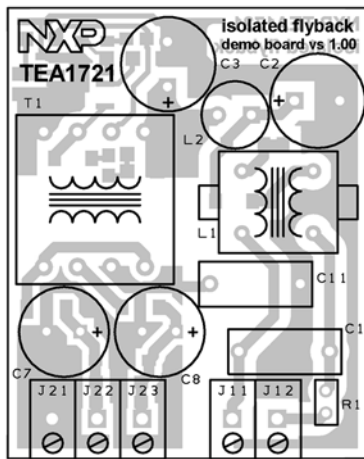
[2] To set the output voltage with greater accuracy, fine-tuning is required.

7. Optional modifications implementation guidelines

- The output voltages are adjusted using resistors R2 and R3. The secondary winding on transformer T1 turns ratio defines the ratio between the two output voltages. Using a different transformer makes other output voltages and/or other output voltage ratios available.
- The maximum output power and output current levels are adjusted using resistor R6. The maximum current allowed in the TEA1721 IC switching MOSFET is 700 mA. Take care that under no circumstances, the peak current in the primary winding of the T1 transformer exceeds 700 mA. Changing the value of R6 also needs a change to the primary inductance value.
- Resistor R1 limits the inrush current. The resistor must be a carbon resistor because metal film resistors can act as a fuse in this position. If no inrush current limiting is required, the resistor can be replaced with a short-circuit.
- EMI-filtering is implemented using separate stages for common mode (L1) and differential mode (L2). Depending on the requirements, the filtering stage can be adapted. For example, inductor L1 can be chosen to ensure that its leakage inductance takes care of differential filtering. As a consequence L2 can be omitted.
- Resistors R8 and R9 form small pre-loads for the converter. When the output voltages are adjusted, also adjust the pre-load resistors to ensure that they consume roughly the same amount of power. Depending on the connected load, eliminate the resistors.
- Zener diodes D6 and D7 implement the elementary output OverVoltage Protection (OVP). When OVP is not needed, eliminate these diodes.
- Capacitors C9 and C10 are used to obtain additional (HF) voltage stability and noise suppression. Eliminate the capacitors when the feature is not needed.
- Capacitor C11 is a Y-capacitor. If the T1 transformer construction provides the required EMI performance without the use of capacitor C11, omit the capacitor.

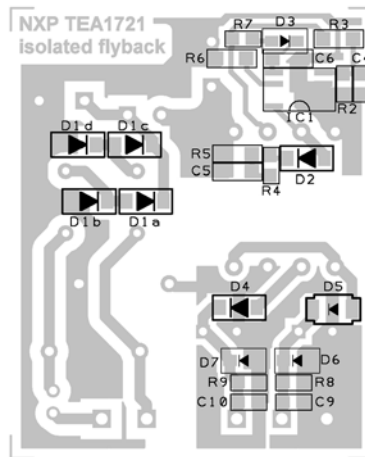
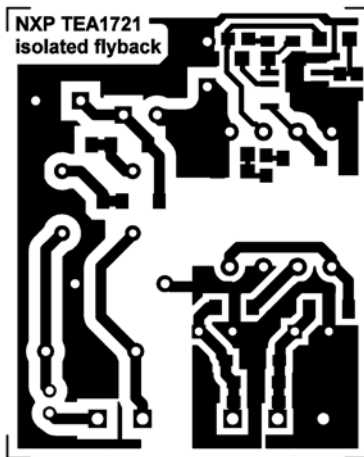
8. Board layout

A 41 mm × 51 mm sized evaluation PCB was created that accommodates an implementation of the TEA1721 isolated universal mains flyback converter.



aaa-002211

a. Top silk screen plus top component placement and drill pattern



aaa-002212

b. Bottom copper and bottom silk screen plus component placement

Fig 6. PCB layout

The bottom silk screen is normally not used in PCB production. Merged with the bottom copper, it is shown here as a component placement reference only. See [Table 2](#) for a list of components.

Table 3. Drill tool table

| Drill tool code | Drill diameter |
|-----------------|----------------|
| C | 1 mm |
| D | 0.9 mm |
| E | 1.3 mm |
| M | 0.8 mm |

Gerber files are available from your local NXP Semiconductor sales representative, on request.

9. Abbreviations

Table 4. Abbreviations

| Acronym | Description |
|---------|---|
| EMC | ElectroMagnetic Compatibility |
| EMI | ElectroMagnetic Interference |
| MOSFET | Metal-Oxide Semiconductor Field-Effect Transistor |
| OCP | OverCurrent Protection |
| OPP | OverPower Protection |
| OVP | OverVoltage Protection |
| OLP | Open-Loop Protection |
| PCB | Printed-Circuit Board |
| PFC | Power Factor Correction |
| SMPS | Switched Mode Power Supply |
| ZVS | Zero Voltage Switching |

10. References

- [1] **TEA1721XT** - Ultra-low standby SMPS controller with integrated power switch
- [2] **AN11060** - TEA172X 5 W to 11 W power supply/USB charger

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